

## Super Low Dross™ Solder Bar Sn96.5/Ag3.0/Cu0.5 1lb (454g) Extruded

### Product Highlights

Extruded High Reliability Solder Bar  
 Manufactured Specifically for High Quality Electronics Manufacturing (EMS, ECM, OEMs)  
 Designed for Solder Pots, Wave Solder Machines and Selective Solder Machines  
 Chip Quik® Super Low Dross™ Solder Bar is Ideal for Through Hole and Surface Mount Soldering  
 High Purity



### Specifications

Alloy: Sn96.5/Ag3.0/Cu0.5  
 Melting Point: 217-220°C (423-428°F)  
 Packaging: 1 lb (454 +/-20 g) bar (Ships bagged. To ensure weight tolerance is met: Full bar and/or fractional bar segments may be combined in each bag.)  
 Shelf Life: Indefinite

### Purity

Element	IPC J-STD-006C	ChipQuik® Super Low Dross™ BARSN96.5AG3.0CU0.5
Silver (Ag)	0.100 %	3.000 %
Aluminum (Al)	0.005 %	< 0.005 %
Arsenic (As)	0.030 %	< 0.030 %
Gold (Au)	0.050 %	< 0.050 %
Bismuth (Bi)	0.100 %	< 0.100 %
Cadmium (Cd)	0.002 %	< 0.002 %
Copper (Cu)	0.080 %	0.500 %
Iron (Fe)	0.020 %	< 0.020 %
Indium (In)	0.100 %	< 0.100 %
Nickel (Ni)	0.010 %	< 0.010 %
Lead (Pb)	0.070 %	< 0.070 %
Tin (Sn)	0.250 %	96.500 %
Zinc (Zn)	0.003 %	< 0.003 %
Antimony (Sb)	0.200 %	< 0.200 %

Tolerances: +/-0.100% (Composition ≤ 1.000%), +/-0.200% (1.000% < Composition ≤ 5.000%), +/-0.500% (Composition > 5.000%)

### Storage and Handling

Store in a dry non-corrosive environment.

### Transportation

This product has no shipping restrictions.

### Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Compliant

### Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): Yes  
 RoHS 3 Directive (EU) 2015/863: Yes